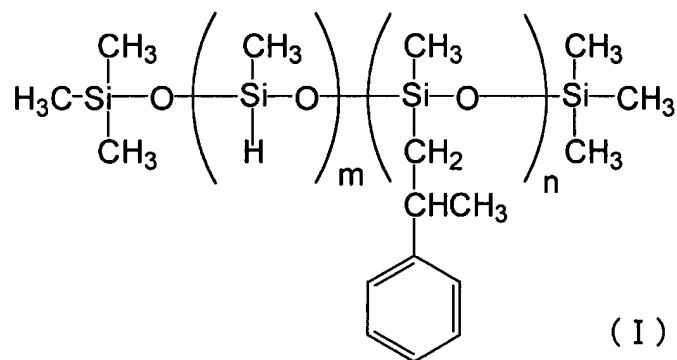


### AMENDMENTS TO THE CLAIMS

**1. (Currently Amended)** A composition capable of being crosslinked to form a pressure sensitive adhesive having a network structure, said composition comprising (A) a polyoxyalkylene polymer having at least one alkenyl group in one molecule, (B) a compound having 1 to 3 hydrosilyl groups on average in one molecule and (C) a hydrosilylation catalyst as essential components.

**2. (Previously Presented)** The composition of claim 1, wherein said compound (B) has a structural formula represented by the following formula (I):



( $1 \leq m \leq 3$ ,  $1 \leq n \leq 8$ ).

**3. (Previously Presented)** The composition of claim 1, wherein said compound (B) has 1.8 - 2.8 hydrosilyl groups on average in one molecule and a number average molecular weight of 400 - 3000.

**4. (Previously Presented)** The composition of claim 1, wherein [amount of hydrosilyl group in said compound (B)]/[total amount of alkenyl group in component (A)] is 0.4 - 0.8.

**5. (Previously Presented)** The composition of claim 1, wherein the polyoxyalkylene polymer having an alkenyl group for said (A) has a number average molecular weight of 6,000 - 50,000.

**6. (Previously Presented)** The composition of claim 1, wherein the polyoxyalkylene polymer for said (A) has 1 - 2 alkenyl groups on average in one molecule.

7. **(New)** The thermally cured composition of claim 1.
8. **(New)** The thermally cured composition of claim 2.
9. **(New)** The thermally cured composition of claim 3.
10. **(New)** The thermally cured composition of claim 4.
11. **(New)** The thermally cured composition of claim 5.
12. **(New)** The thermally cured composition of claim 6.
13. **(New)** An adhesive product comprising the composition of claim 1 thermally cured on a substrate.
14. **(New)** An adhesive product comprising the composition of claim 2 thermally cured on a substrate.
15. **(New)** An adhesive product comprising the composition of claim 3 thermally cured on a substrate.
16. **(New)** An adhesive product comprising the composition of claim 4 thermally cured on a substrate.
17. **(New)** An adhesive product comprising the composition of claim 5 thermally cured on a substrate.
18. **(New)** An adhesive product comprising the composition of claim 6 thermally cured on a substrate.